



S/N 10/723,474

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Examiner: DiLinh Nguyen

Serial No.: 10/723,474

Group Art Unit: 2814

Filed: November 26, 2003

Docket No.: 303.601US2

Title: ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM  
WAFER LEVEL PACKAGING

---

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on October 20, 2006. Please amend the above-identified patent application as follows.